

BRCS40P03DP

Rev.C Mar.-2021

描述 / Descriptions

P 沟道 TO-252 塑封封装场效应管。
P-CHANNEL MOSFET in a TO-252 Plastic Package.

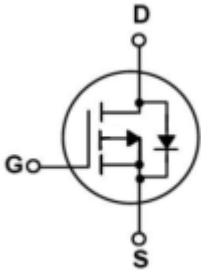
特征 / Features

$R_{DS(on)}$ 小, 大电流输出能力。无卤产品。
Low $R_{DS(on)}$, High Current Capability. Halogen-free Product.

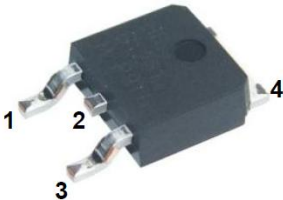
用途 / Applications

交流负载开关, 蓄电池充电/放电保护。
AC-in load switch, Battery protection charge/discharge.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : G

PIN 2 : D

PIN 3 : S

PIN 4 : D

放大及印章代码 / h_{FE} Classifications & Marking

见印章说明。

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter		符号 Symbol	数值 Rating	单位 Unit
Drain-Source Voltage		V_{DSS}	-30	V
Drain Current		$I_D(T_c=25^\circ\text{C})$	-40	A
Drain Current - Pulsed		I_{DM}	-140	A
Gate-Source Voltage		V_{GS}	± 20	V
Avalanche Current		I_{AS}	22	A
Avalanche energy L=0.5mH		E_{AS}	662.7	mJ
Power Dissipation		$P_D(T_c=25^\circ\text{C})$	44	W
		$P_D(T_c=100^\circ\text{C})$	17	W
Junction and Storage Temperature Range		T_j, T_{stg}	-55~150	$^\circ\text{C}$
Maximum Junction-to-Ambient	$t \leq 10\text{s}$	$R_{\theta JA}$	11	$^\circ\text{C/W}$
Maximum Junction-to-Ambient	Steady-State		29	
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	2.8	

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$ $I_D=-250\mu\text{A}$	-30	-36		V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-30\text{V}$ $V_{GS}=0\text{V}$			-1.0	μA
		$V_{DS}=-30\text{V}$ $V_{GS}=0\text{V}$ $T_j=55^\circ\text{C}$			-5.0	μA
Gate-Body Leakage Current Forward	I_{GSS}	$V_{GS}=\pm 20\text{V}$ $V_{DS}=0\text{V}$			± 0.1	μA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ $I_D=250\mu\text{A}$	-1	-1.6	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)1}$	$V_{GS}=-10\text{V}$ $I_D=-30\text{A}$		13	16	m Ω
	$R_{DS(on)2}$	$V_{GS}=-4.5\text{V}$ $I_D=-20\text{A}$		24	28	m Ω
Diode Forward Voltage	V_{SD}	$I_S=-1\text{A}$ $V_{GS}=0\text{V}$		-0.9	-1.2	V

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Input Capacitance	C_{iss}	$V_{DS}=-0V$ $V_{GS}=0V$ $f=1.0MHz$		2530		pF
Output Capacitance	C_{oss}			790		
Reverse Transfer Capacitance	C_{rss}			450		
Gate resistance	R_g	$V_{GS}=0V$ $V_{DS}=0V$ $f=1MHz$		8		Ω
Total Gate Charge	$Q_g(10V)$	$V_{GS}=-10V$ $V_{DS}=-15V$ $I_D=-20A$		50	70	nC
Total Gate Charge	$Q_g(4.5V)$			25	35	
Gate Source Charge	Q_{gs}			9		
Gate Drain Charge	Q_{gd}			12		
Turn-On Delay Time	$t_{d(on)}$	$V_{GS}=-10V$ $V_{DS}=-15V$ $R_L=0.75\Omega$ $R_{GEN}=3\Omega$		12.5		ns
Turn-On Rise Time	t_r			18		
Turn-Off Delay Time	$t_{d(off)}$			125		
Turn-Off Fall Time	t_f			66		

电参数曲线图 / Electrical Characteristic Curve

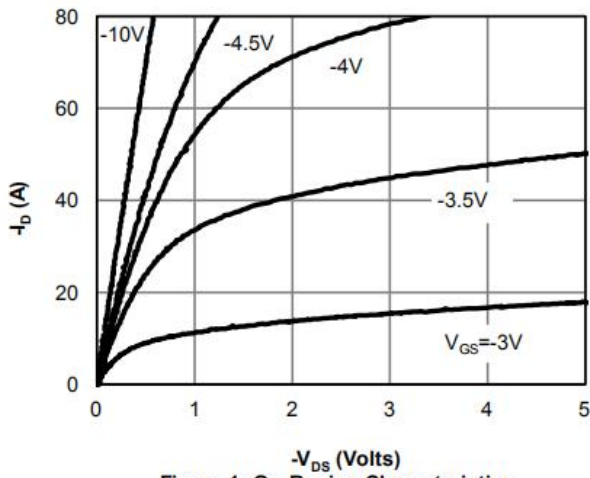


Figure 1: On-Region Characteristics

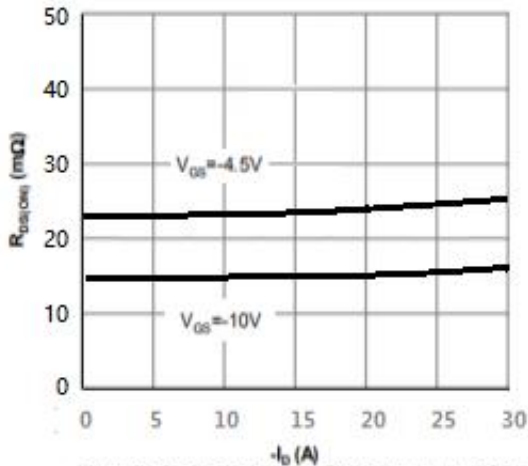
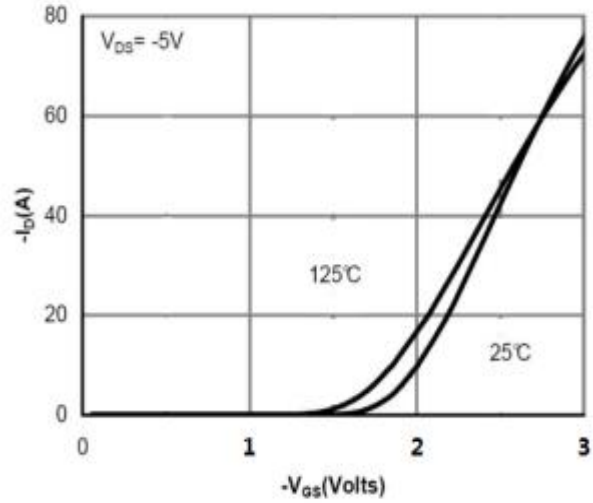


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

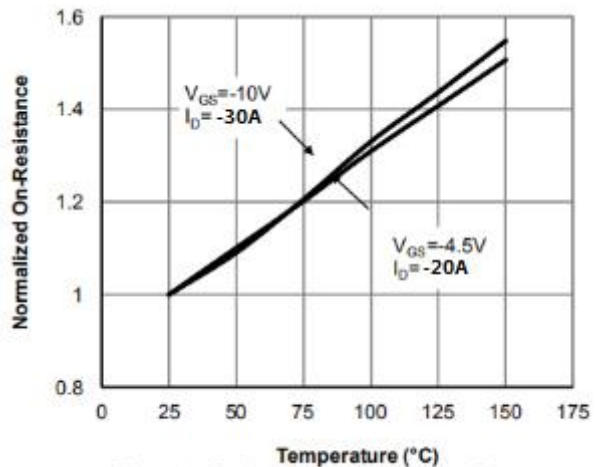


Figure 4: On-Resistance vs. Junction Temperature

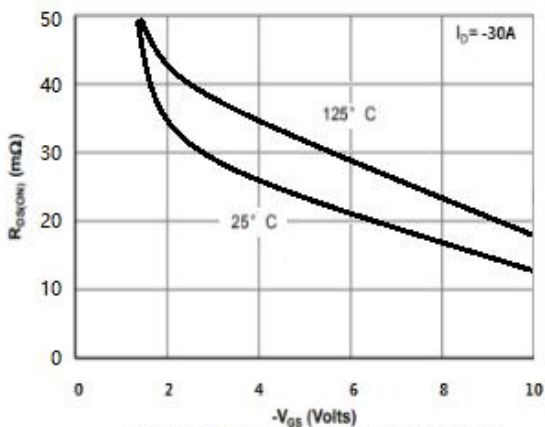


Figure 5: On-Resistance vs. Gate-Source Voltage

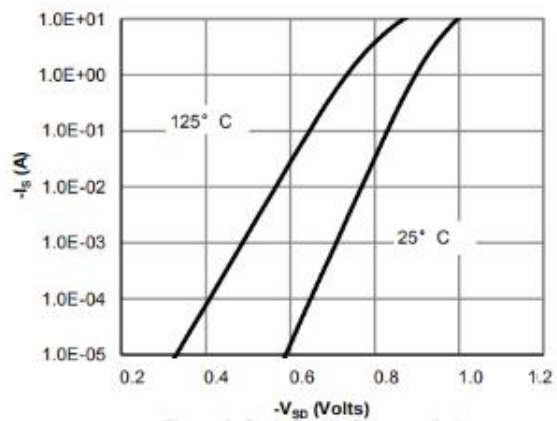


Figure 6: Body-Diode Characteristics

电参数曲线图 / Electrical Characteristic Curve

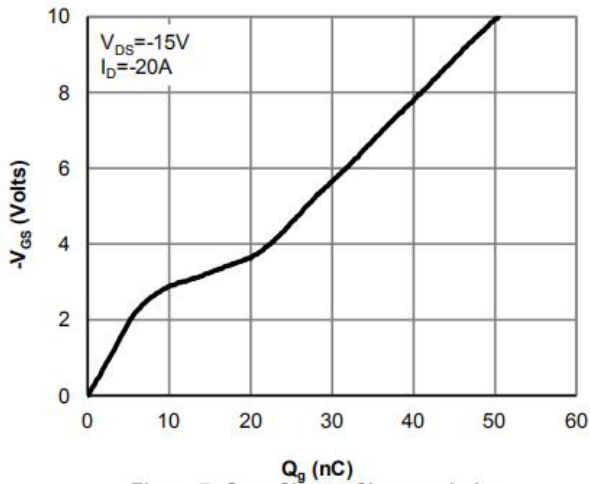


Figure 7: Gate-Charge Characteristics

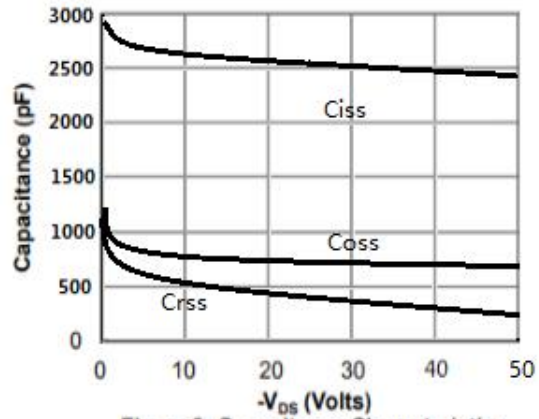


Figure 8: Capacitance Characteristics

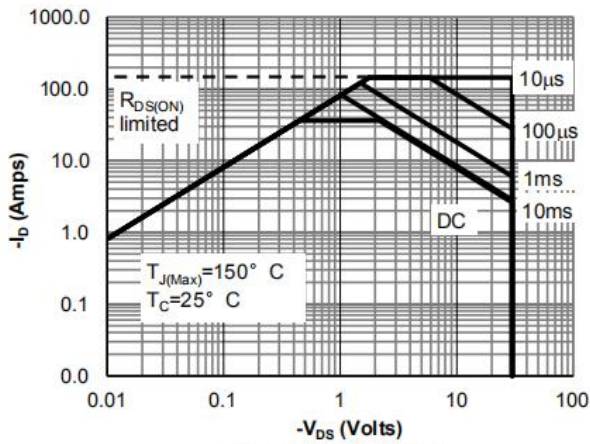


Figure 9: Maximum Forward Biased Safe Operating Area
-Vgs > or equal to -4.5V

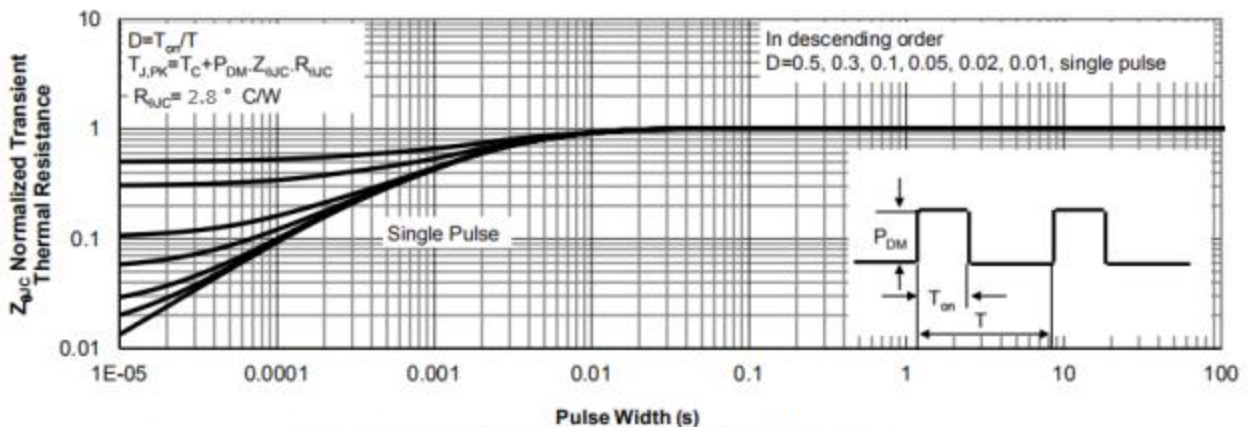
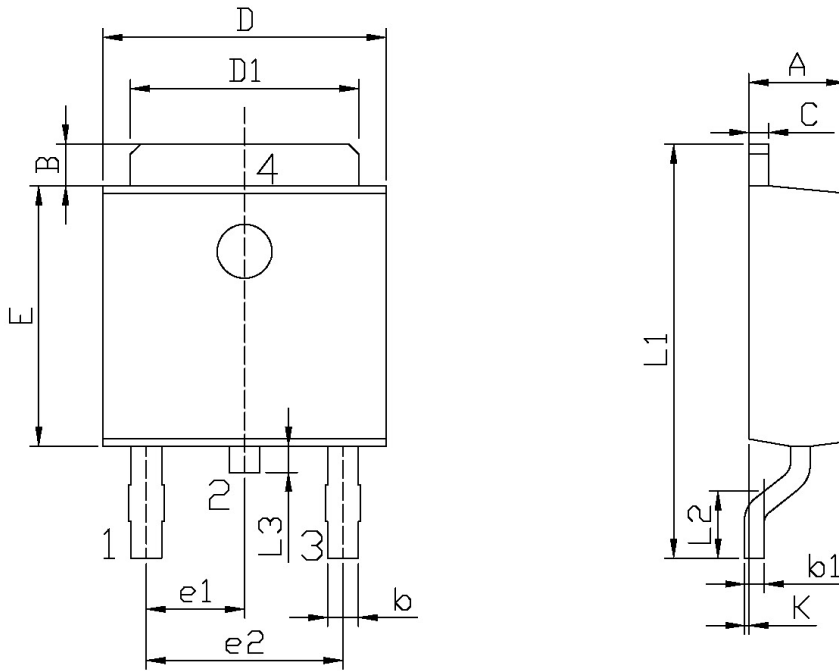


Figure 10: Normalized Maximum Transient Thermal Impedance

外形尺寸图 / Package Dimensions

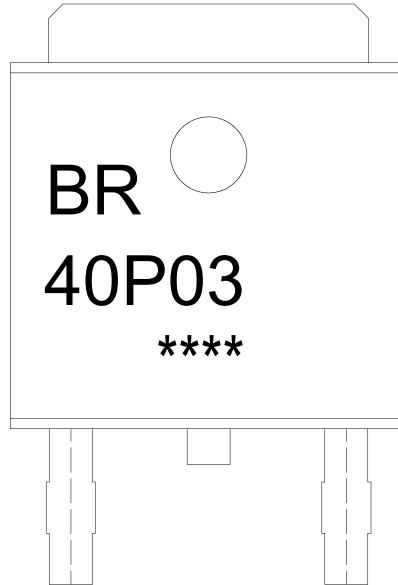


单位: mm

Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.50	0.70	e2	4.43	4.73
b1	0.45	0.55	L1	9.45	9.95
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.10	5.50	K	0.00	0.10

TO-252

印章说明 / Marking Instructions



说明：

BR： 为公司代码

40P03： 为型号代码

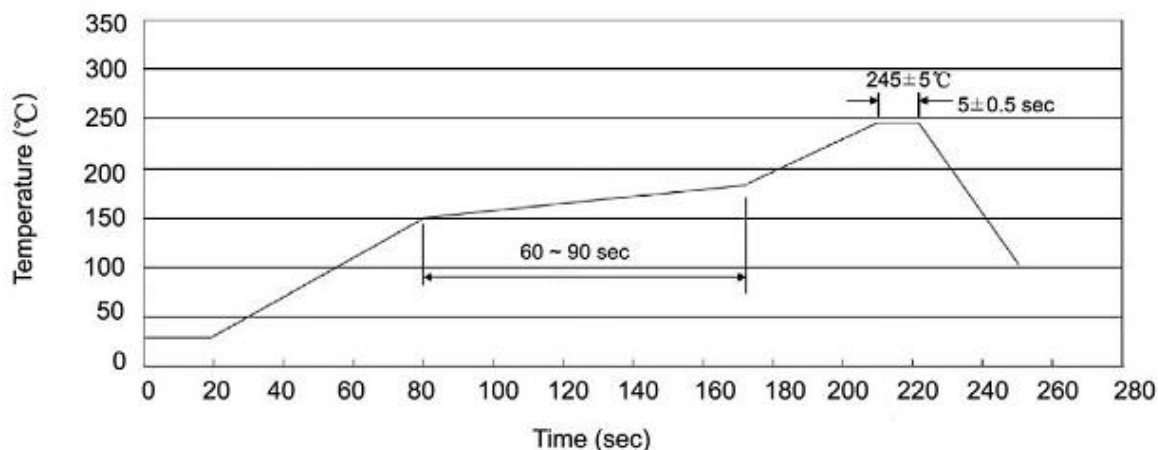
****： 为生产批号代码，随生产批号变化。

Note:

BR: Company Code

40P03: Product Type Code.

****: Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
TO-252	2,500	2	5,000	5	25,000	13" ×16	360×360×50	385×257×392

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

使用说明 / Notices